

Electric drives control: Power modules for (H)EV inverters



Application	Product	V _{CE max} [V]	I _{C max} [A]	U _{CE sat} [V]	R _{th (j·c)} per IGBT switch [K/W]	Features	T _j min [°C]	T _j max [°C]	Package
New IGBT half bridge for (H) EV inverters	MH6560C	650	600	1.40 (@ l _{CE} mod=600A, V _{GE} =15V, ϑ=25°C)	0.076	 3 rdGen. IGBT mold module Wirebond-less contacting of IGBTs and diodes Low inductance layout T-sense (NTC) for overtemperature detection I-sense on chip for short-circuit detection Large, isolated pads for excellent thermal contact ROHS compliant, halogen-free 	-40	150	Mold module with customer specific contacts, 63 mm (L) x 57 mm (W) x 7.5 mm (H)
New IGBT half bridge for (H) EV inverters	MH6530C	650	300	1.40 (@ I _{CE} mod=300A, V _{GE} =15V, ϑ=25°C)	0.14	 3 rdGen. IGBT mold module Wirebond-less contacting of IGBTs and diodes Low inductance layout T-sense (NTC) for overtemperature detection I-sense on chip for short-circuit detection Large, isolated pads for excellent thermal contact ROHS compliant, halogen-free 	-40	150	Mold module with customer specific contacts, 63 mm (L) x 57 mm (W) x 7.5 mm (H)

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